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SNLS166D-MAY 2004-REVISED JULY 2010

LMS202 5V Single Supply TIA/EIA-232 Dual Transceivers

Check for Samples: LMS202

FEATURES

- Single +5V Power Supply
- 230 kbps Data Rate
- On-Board DC-to-DC Converter
- 0.1µF Charge Pump Capacitors
- Drop-In Replacement to Maxim's MAX202

APPLICATIONS

- POS Equipment (Bar Code Reader)
- Hand-Held Equipment
- General Purpose RS-232 Communication

Connection Diagram and Typical Circuit

DESCRIPTION

The LMS202 features two transmitters and two receivers for RS-232 communication. It has a DC-to-DC converter that permits the device to operate with only a single +5V power supply. The on-chip DC-to-DC converter which utilizes four external 0.1µF capacitors to generate dual internal power supplies for RS-232 compatible output levels.

The device meet EIA/TIA-232E and CCITT V.28 specifications up to 230kbits/sec. The LMS202 is available in 16-pin narrow and wide SOIC packages.

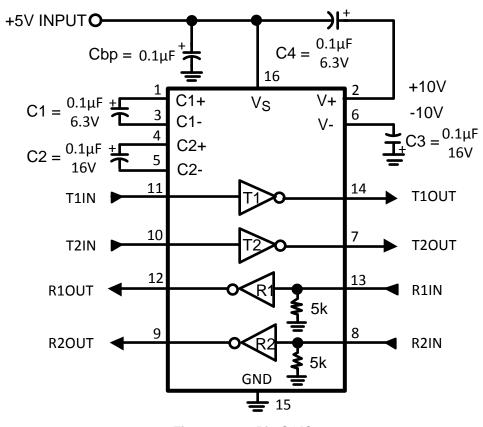


Figure 1. 16-Pin SOIC See D or DW Package

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Pin Number	Pin Name	Pin Function					
1, 3	External capacitor connection pins. Recommended external capacitor C1 = 0.1µF (6.3V)						
2	V+	Positive supply for TIA/EIA-232E drivers. Recommended external capacitor C4 = 0.1µF (6.3V)					
4, 5	C2+, C2-	External capacitor connection pins. Recommended external capacitor C2 = 0.1µF (16V)					
6	V-	Negative supply for TIA/EIA-232E drivers. Recommended external capacitor C3 = 0.1µF (16V)					
7, 14	T1out, T2out	Transmitter output pins conform to TIA/EIA-232E levels. The typical transmitter output swing is ± 8 when loaded $3k\Omega$ load to ground. The open-circuit output voltage swings from (V+ $-$ 0.6V) to V-					
8,13	R1in, R2in	Receiver inputs accept TIA/EIA-232					
9, 12	R1out and R2out	Receiver output pins are TTL/CMOS compatible					
10, 11	Tin1, Tin2	Transmitter input pins are TTL/CMOS compatible. Inputs of transmitter do not have pull-up resistors. Connect all unused transmitter inputs to ground					
15	GND	Ground pin					
16	Vs	Power supply pin for the device, +5V (±10%)					



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

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V _S	-0.3V to 6V				
V+		(V _S - 0.3V) to +14V			
V-		+0.3V to −14V			
Driver Input Voltage, T _{IN}	-0.3V to (V+ +0.3V)				
Receiver Input Voltage, RIN	±30V				
Driver Output Voltage T _O					
Receiver Output Voltage R _O		-0.3 to (V _S +0.3)			
Short Circuit Duration, T _O		Continuous			
ESD Rating	Rating Human Body Model ⁽³⁾				
Machine Model ⁽⁴⁾	·	200V			
Soldering Information	Infrared or Convection (20sec.)	235°C			
Soldering Information Infrared or Convection (20sec.) Junction Temperature		150°C			
Storage Temperature Range	−65°C to +150°C				

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. For ensured specifications and the test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) Human Body Model, 1.5kΩ in series with 100pF
- (4) Machine model, 0Ω in series with 200pF

Operating Ratings

- P									
Supply Voltage V _S									
Commercial (C)	0°C to +70°C								
Industrial (I)	-40°C to +85°C								
D Package	71°C/W								
DW Package	55°C/W								
	Industrial (I) D Package								

(1) The maximum power dissipation is a function of $T_{J(MAX)_i}$, θ_{JA_i} and T_{A_i} . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)_i} - T_A)/\theta_{JA_i}$. All numbers apply for packages soldered directly onto a PC board.

Product Folder Links: LMS202

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Electrical Characteristics

Over recommended operating supply and temperature ranges unless otherwise specified $C1 = C2 = C3 = C4 = Cbp = 0.1 \mu F$

Symbol	Parameter	Conditions	Min ⁽¹⁾	Typ ⁽²⁾	Max ⁽¹⁾	Units
DC Charact	eristics					
I _S	Supply Current	No Load, T _A = 25°C		1	7	mA
Logic						
I _{INPUT}	Input Leakage Current	T _{IN} = 0V to V _S			±10	μA
V _{THL}	Input Logic Theshold Low	T _{IN}			0.8	V
V _{THH}	Input Logic Theshold High	T _{IN}	2.0			V
V _{OL}	TTL/CMOS Output Voltage Low	R _{OUT} , I _{OUT} = 3.2mA			0.4	V
V _{OH}	TTL/CMOS Output Voltage High	R_{OUT} , $I_{OUT} = -1.0$ mA	3.5	V _S −0.1		V
RS-232 Rec	eiver Inputs					
V _{RI}	Receiver Input Voltage Range		-30		+30	V
V _{RTHL}	Receiver Input Theshold Low	V _S = 5V, T _A = 25°C	0.8	1.4		V
V _{RTHH}	Receiver Input Theshold High	V _S = 5V, T _A = 25°C		2	2.4	V
V _{HYST}	Receiver Input Hysteresis	V _S = 5V	0.2	0.6	1.0	V
R _I	Receiver Input Resistance	V _S = 5V, T _A = 25°C	3	5	7	kΩ
RS-232 Trai	nsmitter Outputs			•		
Vo	Transmitter Output Voltage Swing	All transmitters loaded with 3kΩ to GND	±5	±8		V
R _O	Output Resistance	$V_S = V_T = V_T = 0V,$ $V_O = \pm 2V$	300			Ω
Ios	Output Short Circuit Current			±11	±60	mA
Timing Cha	racteristics					
DR	Maximum Data Rate	C_L = 50pF to 1000pF, R_L = 3k Ω to 7k Ω	230			kbps
T _{RPLH} T _{RPHL}	Receiver Propagation Delay	C _L = 150pF		0.08	1	μs
T _{DPLH} T _{DPHL}	Transmitter Propagation Delay	$R_L = 3k\Omega$, $C_L = 2500pF$ All transmitters loaded		2.4		μs
V _{SLEW}	Transition Region Slew Rate	T_A = 25°C, V_S = 5V C_L = 50pF to 1000pF, R_L = 3kΩ to 7kΩ Measured from +3V to -3V or vice versa	3	6	30	V/µs

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⁽¹⁾ All limits are ensured by testing or statistical analysis(2) Typical Values represent the most likely parametric norm.



Typical Characteristics

Transmitter Output High Voltage vs. Load Capacitance

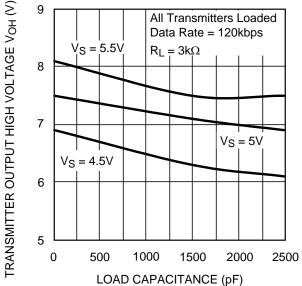


Figure 2.

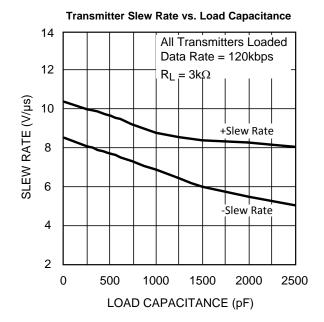


Figure 3.

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APPLICATION INFORMATION

CAPACITOR SELECTION

The recommended capacitors are $0.1\mu F$. However, larger capacitors for the charge pump may be used to minimized ripples on V+ and V- pins.

POWER SUPPLY DECOUPLING

In some applications that are sensitive to power supply noise from the charge pump, place a decoupling capacitor, Cbp, from V_S to GND. Use at least a 0.1 μ F capacitor or the same size as the charge pump capacitors (C1 - C4).

CHARGED PUMP

The dual internal charged-pump provides the $\pm 10V$ to the to transmitters. Using capacitor C1, the charge pump converts +5V to +10V then stores the +10V in capacitor C3. The charge pump uses capacitor C2 to invert the +10V to -10V. The -10V is then stored in capacitor C4.

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